

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 08/26/2022

Details for "LM2937IMP-3.3"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
LM2937IMP-3.3	SNPB	Level-1-260C-UNLIM	Texas Instruments Electronics	DCY   4	6.5 x 3.5 x 1.6	124.2

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
No	Affected	Yes	Affected

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Precious Metals	Gold	7440-57-5	0.196565	100	1000000	0.158288	1583
Sub-Total			0.196565	100	1000000	0.158288	1583
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.571571	74.999967	750000	0.460269	4603
Thermoplastics	Epoxy	85954-11-6	0.190524	25.000033	250000	0.153423	1534
Sub-Total			0.762095	100	1000000	0.613693	6137
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	55.0184	97	970000	44.304692	443047
Copper and Its Alloys	Iron	7439-89-6	1.355608	2.39	23900	1.091631	10916
Copper and Its Alloys	Phosphorus	7723-14-0	0.017016	0.03	300	0.013702	137
Precious Metals	Silver	7440-22-4	0.260912	0.46	4600	0.210105	2101
Zinc and Its Alloys	Zinc	7440-66-6	0.068064	0.12	1200	0.05481	548
Sub-Total			56.72	100	1000000	45.67494	456749
<b>Lead Frame Plating</b>							
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.3915	15	150000	0.315263	3153
Other Nonferrous Metals and Alloys	Tin	7440-31-5	2.2185	85	850000	1.786492	17865
Sub-Total			2.61	100	1000000	2.101756	21018
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	53.88434	89	890000	43.391467	433915
Other Nonferrous Metals and Alloys	Metal Hydroxide	Trade Secret	1.816326	3	30000	1.462634	14626
Thermoplastics	Epoxy	85954-11-6	4.843536	8	80000	3.900356	39004
Sub-Total			60.544202	100	1000000	48.754457	487545
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	3.34902	100	1000000	2.696867	26969
Sub-Total			3.34902	100	1000000	2.696867	26969
<b>Total</b>			124.181882			100	1000000

**Important Note**  
 The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**  
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**  
[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."  
[For additional information, please contact TI customer support.](#)

Signature: [\(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.